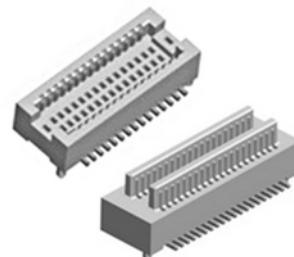


# 5051

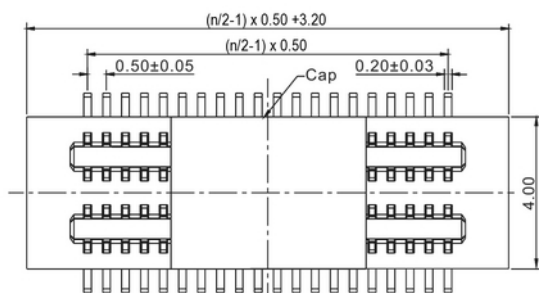
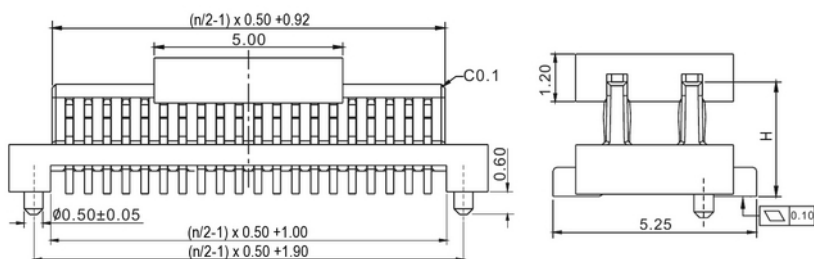
## SMT Board-to-Board Verbinder RM 0,50mm - Kompakttyp SMT Board-to-Board Connectors, 0.50mm Pitch - Compact Type

### Technische Daten / Technical Data

Isolierkörper	Thermoplastischer Kunststoff, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Gold über Nickel
Contact Surface	Gold over nickel
Lötbarkeit	IEC 60512-12A
Solderability	IEC 60512-12A
Durchgangswiderstand	< 50mΩ
Contact Resistance	< 50mΩ
Isolationswiderstand	> 100MΩ
Insulation Resistance	> 100MΩ
Spannungsfestigkeit	100V <sub>AC</sub>
Test Voltage	100V <sub>AC</sub>
Nennspannung	50V AC
Voltage Rating	50V AC
Nennstrom	0,5A
Current Rating	0.5A
Temperaturbereich	-20°C ... +125°C
Temperature Range	-20°C ... +125°C
Verarbeitung	Reflow-Lötverfahren
Processing	Reflow soldering



© W+P PRODUCTS

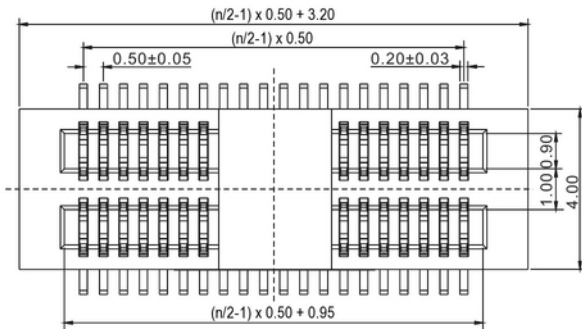
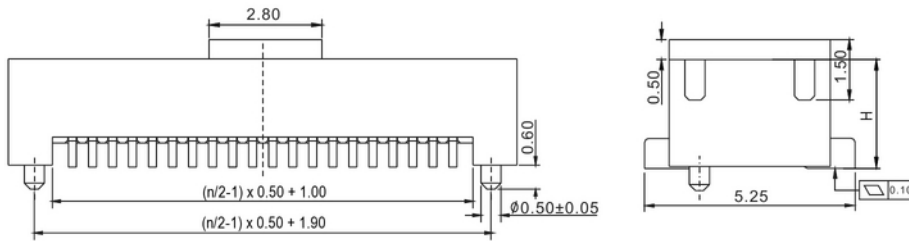


Series	Type*	Contacts*	Plating	Packaging*
<b>5051</b>	<b>1</b>	<b>040</b>	<b>00</b>	<b>PPTR</b>
	1 Stift, H=2,40mm Male, H=2.40mm 2 Stift, H=2,90mm Male, H=2.90mm 3 Stift, H=3,90mm Male, H=3.90mm 4 Stift, H=4,40mm Male, H=4.40mm	10-50 60 80 90 100 120	00 Vergoldet Gold plated	PPST PPTR

# 5051

## SMT Board-to-Board Verbinder RM 0,50mm - Kompakttyp

SMT Board-to-Board Connectors, 0.50mm Pitch - Compact Type



Series

**5051**

Type\*

**5**

5 Buchse; H=2,20mm  
Female; H=2.20mm  
6 Buchse; H=2,70mm  
Female; H=2.70mm  
7 Buchse; H=3,20mm  
Female; H=3.20mm  
8 Buchse; H=3,00mm  
Female; H=3.00mm  
9 Buchse; H=3,50mm  
Female; H=3.50mm

Contacts\*

**040**

10-50 60 80 90 100  
120

Plating

**00**

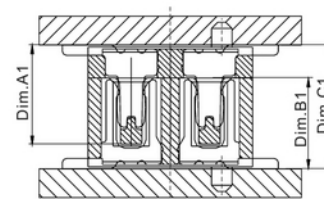
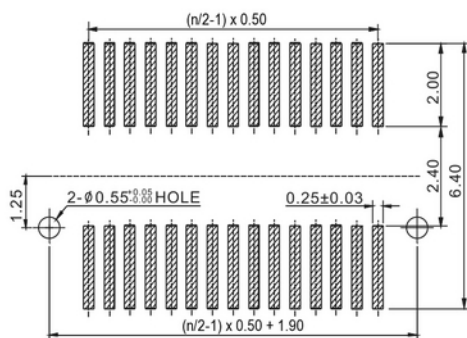
00 Vergoldet  
Gold plated

Packing\*

**PPTR**

PPST In Stangen mit P&P-Pad  
In tubes with P&P-Pad  
PPTR Tape & Reel mit P&P-Pad  
Tape & Reel with P&P-Pad

### Recmd. PCB/Layout



Mating Height Drawing(Ref)

Plug Height Dim.A1	Socket Height Dim.B1	Mating Height Dim.C1
2.40	2.20	3.0
2.90	2.20	3.5
2.90	2.70	4.0
2.90	3.20	4.5
3.90	3.00	5.0
4.40	3.00	5.5
4.40	3.50	6.0

### Lieferformen / Packaging Options:

PPST In Stangen mit Pick&Place-Pad / In tubes with Pick&Place-Pad

PPTR Tape & Reel mit P&P-Pad / Tape & Reel with P&P-Pad

\* Dies ist ein **Bestellbeispiel** -  
bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** -  
please replace by your specifications.

TEL +49 5223 98507-0  
FAX +49 5223 98507-50

**W+P PRODUCTS**

E-MAIL sales@wpro.com  
WEBSITE www.wpro.com

### Reflow-Löttempfehlung

*Reflow Soldering Recommendation*

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150°C
Temperatur Maximum $T_{Smax}$	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich $T_L$	217°C
Verweildauer oberhalb $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur $T_P$	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur $T_P$	Max. 8 min

*Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).*

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150°C
Maximum Temperatur $T_{Smax}$	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature $T_L$	217°C
Duration above $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature $T_P$	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. $T_P$	Max. 8min

